


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

|                             |  |                                      |
|-----------------------------|--|--------------------------------------|
| <b>1.1 Company</b>          |                 | STMicroelectronics International N.V |
| <b>1.2 PCN No.</b>          | AMS/19/11639   |                                      |
| <b>1.3 Title of PCN</b>     | Qualification of TSMC (Taiwan) as additional FE Plant for the listed MEMS 6-AXIS LSM6DSO family. |                                      |
| <b>1.4 Product Category</b> | See Products List  |                                      |
| <b>1.5 Issue date</b>       | 2019-07-03   |                                      |

**2. PCN Team**

|                                  |                           |
|----------------------------------|---------------------------|
| <b>2.1 Contact supplier</b>      |                           |
| <b>2.1.1 Name</b>                | FRANCKE CHRISTIANE        |
| <b>2.1.2 Phone</b>               | +49 89460062128           |
| <b>2.1.3 Email</b>               | christiane.francke@st.com |
| <b>2.2 Change responsibility</b> |                           |
| <b>2.2.1 Product Manager</b>     | Andrea Mario ONETTI       |
| <b>2.1.2 Marketing Manager</b>   | Simone FERRI              |
| <b>2.1.3 Quality Manager</b>     | Michele CALDERONI         |

**3. Change**

|                     |  |   |
|---------------------|--|---|
| <b>3.1 Category</b> | <b>3.2 Type of change</b>  | <b>3.3 Manufacturing Location</b>                                 |
| Transfer            | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication | Agrate, Crolles, TSMC (Taiwan) as FE plants; CALAMBA as BE plant. |

**4. Description of change**

|  |                                   |  |
|--|-----------------------------------|--|
|  | <b>Old</b>                        | <b>New</b>                                       |
| <b>4.1 Description</b>   | FE Plants: ST Agrate, ST Crolles. | FE Plants: ST Agrate, ST Crolles, TSMC (Taiwan). |
| <b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b> | No impact                         |  |

**5. Reason / motivation for change**

|                             |   |
|-----------------------------|---|
| <b>5.1 Motivation</b>       | The introduction of TSMC as additional FE plant shall increase the manufacturing capacity of the listed products. |
| <b>5.2 Customer Benefit</b> | CAPACITY INCREASE   |

**6. Marking of parts / traceability of change**

|                        |                     |
|------------------------|---------------------|
| <b>6.1 Description</b> | Dedicated FG codes. |
|------------------------|---------------------|

**7. Timing / schedule**

|  |              |
|--|--------------|
| <b>7.1 Date of qualification results</b>   | 2019-11-04   |
| <b>7.2 Intended start of delivery</b>      | 2020-01-27   |
| <b>7.3 Qualification sample available?</b> | Upon Request |

**8. Qualification / Validation**

|   |             |                   |  |
|---|-------------|-------------------|--|
| <b>8.1 Description</b>                                    |             |                   |  |
| <b>8.2 Qualification report and qualification results</b> | In progress | <b>Issue Date</b> |  |

**9. Attachments (additional documentations)**

11639 Public product.pdf

**10. Affected parts**

| 10. 1 Current           |                         | 10.2 New (if applicable) |
|-------------------------|-------------------------|--------------------------|
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
| 2980917                 | LSM6DSOTR               |                          |
| 3011638                 | LSM6DSOXTR              |                          |

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